

ABSTRACT

A semiconductor encapsulating epoxy resin composition
5 is provided comprising (A) an epoxy resin, (B) a phenolic
resin curing agent, (C) a molybdenum compound, (D-i) an
organopolysiloxane, (D-ii) an organopolysiloxane cured
product, or (D-iii) a block copolymer obtained by reacting
an epoxy resin or alkenyl group-bearing epoxy resin with an
10 organohydrogenpolysiloxane, and (E) an inorganic filler.
The composition has improved moldability and solder crack
resistance while exhibiting high flame retardance despite
the absence of halogenated epoxy resins and antimony oxide.